



May 20, 2008

To: Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Fr: Stephen B. Ackerman, Reg. No. 37,761
28 Davis Avenue
Poughkeepsie, N.Y. 12603

Subject:

Serial No.	10/826,752	04/16/04
ROMEO EMMANUEL P. ALVAREZ		
"METHOD FOR FORMING A WAFER LEVEL CHIP SCALE PACKAGE, AND PACKAGE FORMED THEREBY"		
Grp. Art Unit: 2813	JAMES M. MITCHELL	

RESPONSE TO FINAL OFFICE ACTION

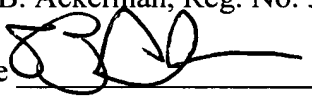
Dear Sir:

In response to the Final Office Action dated January 10, 2008, please amend the above-identified application for patent as follows:

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on ~~June 10~~ June 10, 2008.

Stephen B. Ackerman, Reg. No. 37,761

Signature Date June 10, 2008